FOR ADDITIONAL INFORMATION CONTACT:

Phone: (518) 452-2880 E-mail: info@yincae.com



YINCAE Advanced Materials, LLC

19 Walker Way, Albany, NY 12205 (518) 452-2880 www.yincae.com

FOR IMMEDIATE RELEASE

Press Release

World's First Commercially Available Diamond Filled Underfill: SMT 158D8

(Albany, NY) January 18, 2021 YINCAE is excited to announce that we have developed SMT 158D8 a high thermal conductive underfill that is capillary and fast flowing, and an easy reworkable liquid epoxy.

SMT 158D8 is the world's first (and only) commercially available diamond filled underfill. SMT 158D8 has a thermal conductivity of >6 W/mK, can flow into small gaps easily with no phase separation, high salt-moisture resistance, and excellent adhesion. Furthermore, the performance of the SMT 158D8 drop test has been improved by two orders of magnitude compared with that with the use of solder paste. The highlight of the SMT 158D8 is its ability to lower CPU (POP) temperatures by 10 °C.

This material can be used as a underfill for flip chip, chip scale package, ball grid array devices, package on package, and land grid array application. It is also suitable for bare chip protection in a variety of advanced packages such as memory cards, chip carriers, hybrid circuits and multichip modules. It is designed for high production and an environment where process speed and thermal dissipation are key concerns.

For more information on YINCAE's SMT 158D8 underfill, or to learn more about the YINCAE product range, please email us at: info@yincae.com. You can also find more information by visiting our website at: www.yincae.com.

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Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.